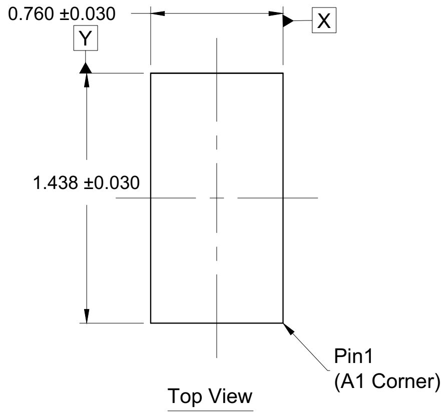
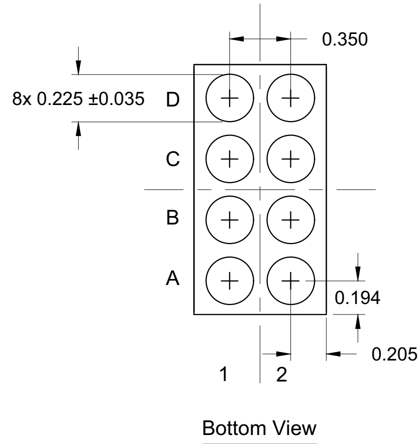
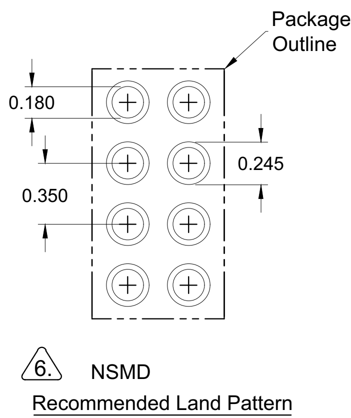
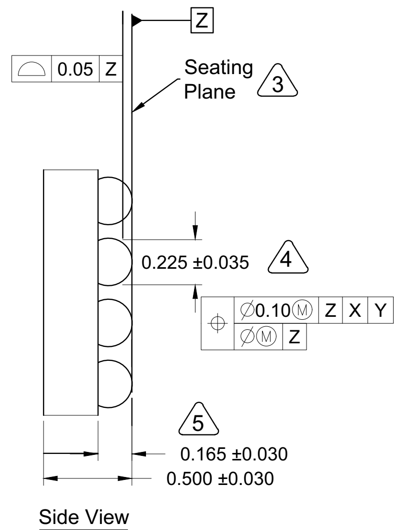
Package Outline Drawing

W2x4.8A
8 Ball Wafer Level Chip Scale Package (WLCSP 0.35mm Pitch)
Rev 1, 8/2023









NOTES:

1. All dimensions are in millimeters.
2. Dimensions and tolerances per ASMEY 14.5-1994
3. The spherical crowns of the bump define primary datum Z and the seating plane.
4. Dimension is measured at the maximum bump diameter parallel to primary datum Z.
5. Bump position designation per JESD 95-1, SPP-010.
6. NSMD refers to non-solder mask-defined pad design per techbrief TB451.